onsemi

**WLCSP10 0.77x2.27x0.33**
CASE 567YK
ISSUE A

DATE 14 SEP 2020
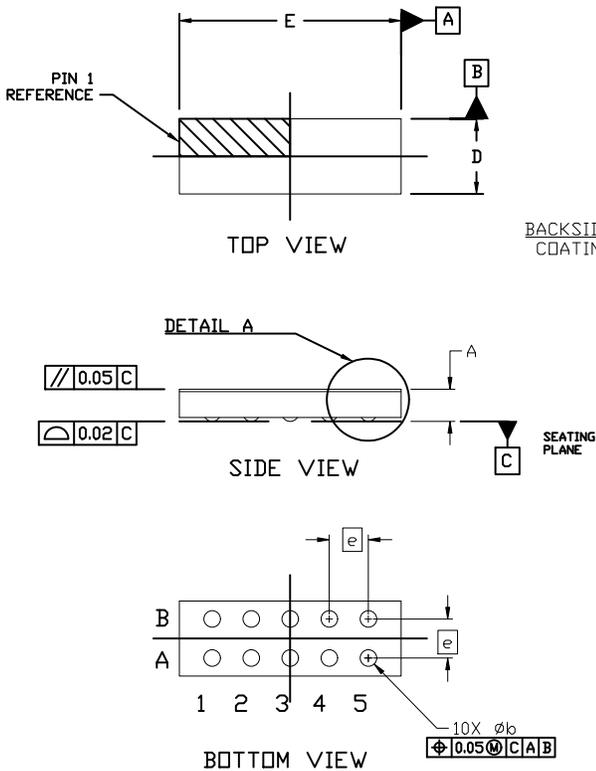
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

TOP VIEW

DETAIL A

SIDE VIEW

BACKSIDE COATING

DETAIL A

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.31	0.33	0.35
A1	0.034	0.040	0.046
A2	0.2525	0.265	0.2775
A3	0.025 REF		
b	0.15	0.17	0.19
D	0.720	0.770	0.820
E	2.220	2.270	2.320
e	0.40 BSC		

BOTTOM VIEW

10X ⌀b

RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

A1 BALL

0.40 PITCH

0.40 PITCH

10X ⌀0.14
Cu-PAD AT BOTTOM
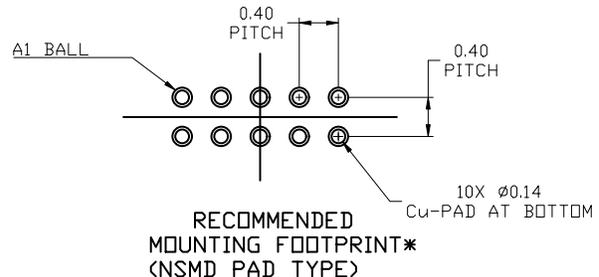
* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*
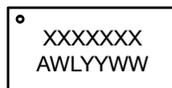
XXXXXXX
AWLYYWW

XXXX = Specific Device Code
A   = Assembly Location
WL   = Wafer Lot
YY   = Year
WW   = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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